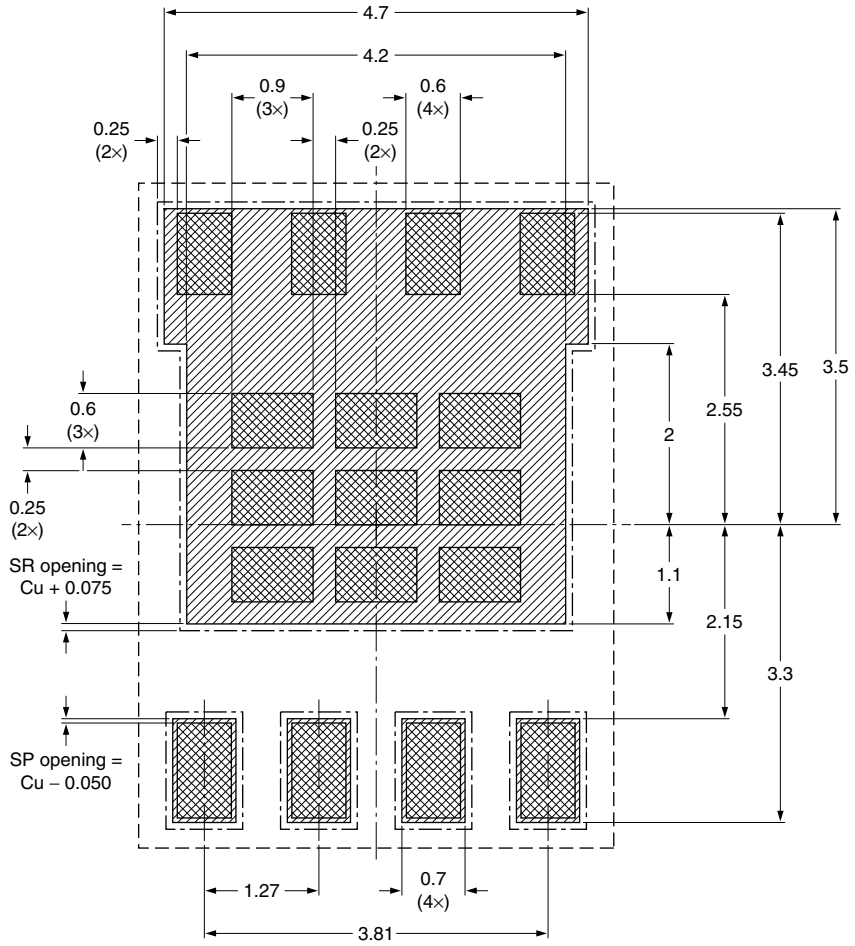
Reflow soldering footprint

Footprint information for reflow soldering **SOT669**



solder lands — solder paste 125 µm stencil

solder resist — occupied area

Dimensions in mm

sot669_fr

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